UNICOM Engineering E-1800 R7 High Reliability Medium Density Enterprise Computing Systems





# **UNICOM Engineering E-1800 R7 High Reliability Medium Density Enterprise Computing Systems Instructions**

Home » UNICOM Engineering » UNICOM Engineering E-1800 R7 High Reliability Medium Density Enterprise Computing Systems Instructions ™

#### **Contents**

- 1 UNICOM Engineering E-1800 R7 High-Reliability Medium Density Enterprise Computing Systems
- **2 PRODUCT DISASSEMBLY INSTRUCTIONS**
- 3 Annex A
- **4 Specifications**
- 5 FAQ
- 6 Documents / Resources
  - **6.1 References**
- **7 Related Posts**



**UNICOM** Engineering E-1800 R7 High-Reliability Medium Density Enterprise Computing Systems



**Unit Disassembly for WEEE** 

Revision	Date	MR#	Revised By	Description of Changes
01	06/29/2023	37592	John Loos	Draft
0A	11/28/2023	37592	John Loos	Released

**NOTE:** Disconnect any AC Power Cords or shut off any DC power source attached to the power supplies and then remove any wires connected to the DC power supplies before disassembly of the unit.

#### PRODUCT DISASSEMBLY INSTRUCTIONS

Most parts can be removed easily by hand. In some cases, common household tools such as Philips and/or flathead screwdrivers may be necessary. Some components may require needle-nose pliers. Instructions for removing parts in this product can be found in the Intel System Integration and Service Guide documentation. All removed components should be disposed of in the appropriate recycling bin. The most recent documentation for this server can be found online at:

https://www.intel.com/content/www/us/en/products/details/servers/server-systems/server-m50fcp/docs.html

Revision 1.2 is attached here for reference:



• Intel Server System M50FCP1UR TPS Re

Images shown are representative of the product and may vary depending on the actual configuration.

Example: 12-drive, E-1800 R7 Server with lid:]



Example: E-2900 R7 Internal View



Recycling/Material Code	Important Information			
Material /Components, which must be removed and treated separately				
Lithium Battery	Battery-free of hazardous substances, installed in the socket on the motherboard			
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser, Power Supp ly, and DVD adapter PCB			
Disk Drives	Hard Drive, DVD Drive, Solid State Drive			
Material /Components, which can distur	b certain recycling processes			
Aluminum	Heat sink, handles			
Material /Components, through which be	enefits can normally be achieved			
Cold Rolled Steel	Top cover, chassis bottom, and rails			
* ABS	Pushbuttons, Shroud			
Cables	Distributed in device			
Fans				
Special notes				
* Flame retardant of plastics does not con	tain PBB and PBDE.			

# Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>	
Scope of information sheet:	< Product category as in Annex IA of WEEE Directive, or type of equipme nt as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >	

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	Lithium battery Located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing ruminated flame retardants other than in Printed Cir cuit Assemblies ***	NONE

Component or Material	Remarks / Location
Liquid Crystal Displays with a surface greater than 100 cm2	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diamete r > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibers	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector  cont acts
Gasses – which fall under Regulation (EC) 2037/2000 and all hydroca rbons (HC).	NONE
Components with pressurized gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts that need special attention *****	
(diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in D irective 2006/122/EC	NONE

location of a substance/component is requested, it is at the part level, e.g. main board, housing, etc

- Internal means that batteries can only be removed by opening the product using (a) tool(s).
- Substances are considered to be in the product if present above the levels specified in Commission Decision 2011/65/EU (RoHS Directive) or if their use is permitted through exemptions in Annex III of this directive.
- To be coherent with the industry's current standards and practices on tracking of plastic parts, the Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weigh more than 25 g.
- The substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments
- Needs of an equivalent nature as those for maintenance, service manuals, and installation for safety purposes.

# **Specifications**

• Product Name: E-1800 R7 Unit

Document Number / Disk File: 597-2001-00
 Assemblies Covered: E-1800 R7 (786-7327-00)

#### **FAQ**

### Q: What tools are recommended for disassembling the E-1800 R7 Unit?

A: Common household tools such as Philips and flat-head screwdrivers, as well as needle-nose pliers, may be required for disassembly.

#### Q: Where can I find the most recent documentation for this server?

A: The latest documentation can be accessed online at the provided Intel website link.

# Q: How should I dispose of removed components?

A: All removed components should be disposed of in the appropriate recycling bin following electronic waste disposal guidelines.

#### **Documents / Resources**



<u>UNICOM Engineering E-1800 R7 High Reliability Medium Density Enterprise Computing S</u>
<u>ystems</u> [pdf] Instructions

E-1800 R7, E-1800 R7 High Reliability Medium Density Enterprise Computing Systems, High R eliability Medium Density Enterprise Computing Systems, Reliability Medium Density Enterprise Computing Systems, Density Enterprise Computing Systems, Enterprise Computing Systems, Systems, Systems

#### References

• User Manual

SIG, Inc. The "Wi-Fi®" word mark and logos are registered trademarks owned by the Wi-Fi Alliance. Any use of these marks on this website does not imply any affiliation with or endorsem	nent.